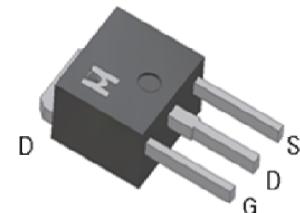
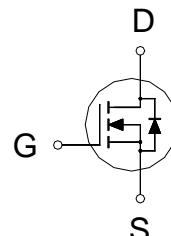


N-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV _{DSS}	600V
R _{DSON} (MAX.)	2.5Ω
I _D	4A



UIS, 100% Tested

Pb-Free Lead Plating & Halogen Free



ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V _{GS}	±30	V
Continuous Drain Current	T _C = 25 °C	I _D	4	A
	T _C = 100 °C		2.5	
Pulsed Drain Current ¹		I _{DM}	16	
Avalanche Current		I _{AS}	3	
Avalanche Energy	L = 3mH, I _D =3A, R _G =25Ω	E _{AS}	13.5	mJ
Repetitive Avalanche Energy ²	L = 0.5mH	E _{AR}	2.25	
Power Dissipation	T _C = 25 °C	P _D	30	W
	T _C = 100 °C		12	
Operating Junction & Storage Temperature Range		T _j , T _{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	R _{θJC}	4.2	4.2	°C / W
Junction-to-Ambient	R _{θJA}		110	

¹Pulse width limited by maximum junction temperature.

²Duty cycle ≤ 1%

ELECTRICAL CHARACTERISTICS ($T_c = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	600			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2	3	5	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 30V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 600V, V_{GS} = 0V$			10	μA
		$V_{DS} = 480V, V_{GS} = 0V, T_J = 125^\circ\text{C}$			25	
Drain-Source On-State Resistance ¹	$R_{DS(\text{ON})}$	$V_{GS} = 10V, I_D = 2A$		2.1	2.5	Ω
Forward Transconductance ¹	g_{fs}	$V_{DS} = 25V, I_D = 2A$		2		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1\text{MHz}$		455		pF
Output Capacitance	C_{oss}			49		
Reverse Transfer Capacitance	C_{rss}			2.9		
Total Gate Charge ^{1,2}	Q_g	$V_{DS} = 300V, V_{GS} = 10V, I_D = 1A$		8.4		nC
Gate-Source Charge ^{1,2}	Q_{gs}			2.2		
Gate-Drain Charge ^{1,2}	Q_{gd}			2.2		
Turn-On Delay Time ^{1,2}	$t_{d(on)}$	$V_{DS} = 300V, I_D = 1.5A, V_{GS} = 10V, R_G = 20\Omega$		20		nS
Rise Time ^{1,2}	t_r			30		
Turn-Off Delay Time ^{1,2}	$t_{d(off)}$			20		
Fall Time ^{1,2}	t_f			30		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_c = 25^\circ\text{C}$)						
Continuous Current	I_S				4	A
Pulsed Current ³	I_{SM}				16	
Forward Voltage ¹	V_{SD}	$I_F = I_S, V_{GS} = 0V$			1.4	V
Reverse Recovery Time	t_{rr}	$I_F = I_S, dI_F/dt = 100A/\mu\text{s}$		0.3		μs
Reverse Recovery Charge	Q_{rr}				1.0	μC

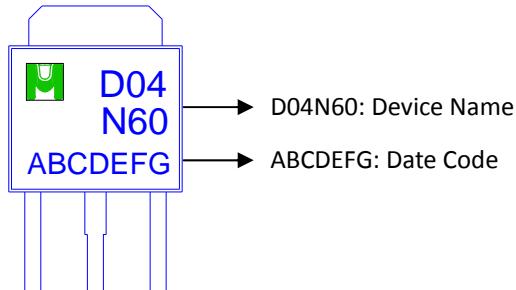
¹Pulse test : Pulse Width $\leq 300\ \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

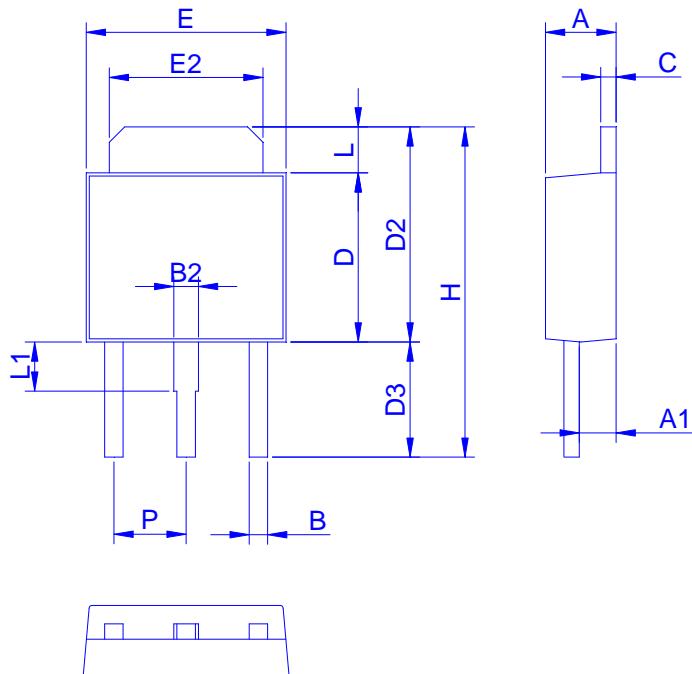
³Pulse width limited by maximum junction temperature.

Ordering & Marking Information:

Device Name: EMD04N60CS for IPAK (TO-251)



Outline Drawing



Dimension in mm

Dimension	A	A1	B	B2	C	D	D2	D3	E	E2	H	L	L1	P
Min.	2.10	0.90	0.40	0.60	0.40	5.30	6.70	3.40	6.30	4.80	10.2	0.89	0.90	2.10
Max.	2.50	1.50	0.90	1.15	0.60	6.25	7.30	4.30	6.80	5.50	11.5	1.40	1.80	2.50

TYPICAL CHARACTERISTICS

